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Pixus Announces New 3U OpenVPX Backplane To PCIe Gen3 Speeds

Waterloo, Ontario — Nov 03, 2017 – Pixus Technologies, a provider of embedded computing and enclosure solutions, has released a new 3U OpenVPX high-speed backplane in the 6-slot size.

The 3U OpenVPX backplane meets the BKP-DIS06-15.2.14 profile per VITA 65.   The PCIe Gen3 capable backplane features a high-grade laminate material and back-drilling of vias.   Rear Transition Module (RTM) connectors are optional for rear I/O access.   Conformal coating and customized versions of the backplane are also available.

The slot pitch of the 3U OpenVPX backplane is 1.0", with 0.80" versions available upon request. Pixus also offers 3U 6-slot backplanes in other VITA 65 backplane profile and speed options.

Pixus provides OpenVPX enclosures, backplanes, components, and accessories. The company also offers mounting rails and subrack components for CompactPCI Serial, CompactPCI, VME64x, and other architectures.

About Pixus Technologies

Leveraging over 25 years of innovative standard products, the Pixus team is comprised of industry experts in electronics packaging. Founded in 2009 by senior management from Kaparel Corporation, a Rittal company, Pixus Technologies' embedded backplanes and systems are focused primarily on ATCA, OpenVPX, MicroTCA, and custom designs.   Pixus also has an extensive offering of VME-based and cPCI-based solutions.   In May 2011, Pixus Technologies became the sole authorized North and South American supplier of the electronic packaging products previously offered by Kaparel Corporation and Rittal.